

## Definition of Terms

In this document, some specifications may be designated as Advance or Preliminary. These terms are defined as follows:

**Advance:** Initial estimates based on simulation and/or extrapolation from other speed grades, devices, or families. Values are subject to change. Use as estimates, not for production.

**Preliminary:** Based on preliminary characterization. Further changes are not expected.

**Unmarked:** Specifications not identified as either Advance or Preliminary are to be considered Final.

Except for pin-to-pin input and output parameters, the AC parameter delay specifications included in this document are derived from measuring internal test patterns. All limits are representative of worst-case supply voltage and junction temperature conditions. Typical numbers are based on measurements taken at a nominal  $V_{CCINT}$  level of 2.5V and a junction temperature of 25°C. The parameters included are common to popular designs and typical applications. **All specifications are subject to change without notice.**

## DC Specifications

### Absolute Maximum Ratings<sup>(1)</sup>

Symbol	Description		Min	Max	Units	
$V_{CCINT}$	Supply voltage relative to GND <sup>(2)</sup>		-0.5	3.0	V	
$V_{CCO}$	Supply voltage relative to GND <sup>(2)</sup>		-0.5	4.0	V	
$V_{REF}$	Input reference voltage		-0.5	3.6	V	
$V_{IN}$	Input voltage relative to GND <sup>(3)</sup>		5V tolerant I/O <sup>(4)</sup>	-0.5	5.5	V
			No 5V tolerance <sup>(5)</sup>	-0.5	$V_{CCO} + 0.5$	V
$V_{TS}$	Voltage applied to 3-state output		5V tolerant I/O <sup>(4)</sup>	-0.5	5.5	V
			No 5V tolerance <sup>(5)</sup>	-0.5	$V_{CCO} + 0.5$	V
$T_{STG}$	Storage temperature (ambient)		-65	+150	°C	
$T_J$	Junction temperature		-	+125	°C	

#### Notes:

1. Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those listed under Operating Conditions is not implied. Exposure to Absolute Maximum Ratings conditions for extended periods of time may affect device reliability.
2. Power supplies may turn on in any order.
3.  $V_{IN}$  should not exceed  $V_{CCO}$  by more than 3.6V over extended periods of time (e.g., longer than a day).
4. Spartan-II I/Os are 5V Tolerant whenever the LVTTL, LVCMS2, or PCI33\_5 signal standard has been selected. With 5V Tolerant I/Os selected, the Maximum DC overshoot must be limited to either +5.5V or 10 mA, and undershoot must be limited to either -0.5V or 10 mA, whichever is easier to achieve. The Maximum AC conditions are as follows: The device pins may undershoot to -2.0V or overshoot to +7.0V, provided this over/undershoot lasts no more than 11 ns with a forcing current no greater than 100 mA.
5. Without 5V Tolerant I/Os selected, the Maximum DC overshoot must be limited to either  $V_{CCO} + 0.5$  V or 10 mA, and undershoot must be limited to -0.5V or 10 mA, whichever is easier to achieve. The Maximum AC conditions are as follows: The device pins may undershoot to -2.0V or overshoot to  $V_{CCO} + 2.0$  V, provided this over/undershoot lasts no more than 11 ns with a forcing current no greater than 100 mA.
6. For soldering guidelines, see the Packaging Information on the Xilinx website: [www.xilinx.com/partinfo/pkgs.htm](http://www.xilinx.com/partinfo/pkgs.htm)

## Recommended Operating Conditions

Symbol	Description		Min	Max	Units
$T_J$	Junction temperature <sup>(1)</sup>	Commercial	0	85	°C
		Industrial	-40	100	°C
$V_{CCINT}$	Supply voltage relative to GND <sup>(2,5)</sup>	Commercial	2.5 - 5%	2.5 + 5%	V
		Industrial	2.5 - 5%	2.5 + 5%	V
$V_{CCO}$	Supply voltage relative to GND <sup>(3,5)</sup>	Commercial	1.4	3.6	V
		Industrial	1.4	3.6	V
$T_{IN}$	Input signal transition time <sup>(4)</sup>		-	250	ns

**Notes:**

- At junction temperatures above those listed as Operating Conditions, all delay parameters increase by 0.35% per °C.
- Functional operation is guaranteed down to a minimum  $V_{CCINT}$  of 2.25V (Nominal  $V_{CCINT}$  - 10%). For every 50 mV reduction in  $V_{CCINT}$  below 2.375V (nominal  $V_{CCINT}$  - 5%), all delay parameters increase by 3%.
- Minimum and maximum values for  $V_{CCO}$  vary according to the I/O standard selected.
- Input and output measurement threshold is ~50% of  $V_{CCO}$ .
- Supply voltages may be applied in any order desired.

## DC Characteristics Over Operating Conditions

Symbol	Description		Min	Typ	Max	Units	
$V_{DRINT}$	Data Retention $V_{CCINT}$ voltage (below which configuration data may be lost)		2.0	-	-	V	
$V_{DRIO}$	Data Retention $V_{CCO}$ voltage (below which configuration data may be lost)		1.2	-	-	V	
$I_{CCINTQ}$	Quiescent $V_{CCINT}$ supply current <sup>(1)</sup>	XC2S15	Commercial	-	10	30 mA	
			Industrial	-	10	60 mA	
		XC2S30	Commercial	-	10	30 mA	
			Industrial	-	10	60 mA	
		XC2S50	Commercial	-	12	50 mA	
			Industrial	-	12	100 mA	
		XC2S100	Commercial	-	12	50 mA	
			Industrial	-	12	100 mA	
		XC2S150	Commercial	-	15	50 mA	
			Industrial	-	15	100 mA	
		XC2S200	Commercial	-	15	75 mA	
			Industrial	-	15	150 mA	
$I_{CCOQ}$	Quiescent $V_{CCO}$ supply current <sup>(1)</sup>		-	-	2	mA	
$I_{REF}$	$V_{REF}$ current per $V_{REF}$ pin		-	-	20	µA	
$I_L$	Input or output leakage current <sup>(2)</sup>		-10	-	+10	µA	
$C_{IN}$	Input capacitance (sample tested)	$V_Q$ , $CS$ , $TQ$ , $PQ$ , $FG$ packages		-	8	pF	
$I_{RPU}$	Pad pull-up (when selected) @ $V_{IN} = 0V$ , $V_{CCO} = 3.3V$ (sample tested) <sup>(3)</sup>		-	-	0.25	mA	
$I_{RPD}$	Pad pull-down (when selected) @ $V_{IN} = 3.6V$ (sample tested) <sup>(3)</sup>		-	-	0.15	mA	

**Notes:**

- With no output current loads, no active input pull-up resistors, all I/O pins 3-stated and floating.
- The I/O leakage current specification applies only when the  $V_{CCINT}$  and  $V_{CCO}$  supply voltages have reached their respective minimum Recommended Operating Conditions.
- Internal pull-up and pull-down resistors guarantee valid logic levels at unconnected input pins. These pull-up and pull-down resistors do not provide valid logic levels when input pins are connected to other circuits.

## Supply Current Requirements During Power-On

Spartan-II FPGAs require that a minimum supply current  $I_{CCPO}$  be provided to the  $V_{CCINT}$  lines for a successful power-on. If more current is available, the FPGA can consume more than  $I_{CCPO}$  min., though this cannot adversely affect reliability.

A maximum limit for  $I_{CCPO}$  is not specified. Be careful when using foldback/crowbar supplies and fuses. It is possible to control the magnitude of  $I_{CCPO}$  by limiting the supply current available to the FPGA. A current limit below the trip level will avoid inadvertently activating over-current protection circuits.

Symbol	Description		Min <sup>(1)</sup>	Max	Units
$I_{CCPO}$	Total $V_{CCINT}$ supply current required during power-on	$0^{\circ}\text{C} \leq T_J \leq 100^{\circ}\text{C}$ <sup>(2)</sup>	500	-	mA
		$-40^{\circ}\text{C} \leq T_J < 0^{\circ}\text{C}$	2	-	A
$T_{CCPO}$	$V_{CCINT}$ ramp time <sup>(3,4)</sup>		-	50	ms

### Notes:

1. The  $I_{CCPO}$  requirement applies for a brief time (commonly only a few milliseconds) when  $V_{CCINT}$  ramps from 0 to 2.5V.
2. Applies to both Commercial and Industrial devices.
3. The ramp time is measured from GND to  $V_{CCINT}$  max on a fully loaded board.
4.  $V_{CCINT}$  must not dip in the negative direction during power on.
5. For more information on designing to meet the power-on specifications, refer to the application note [XAPP450 "Power-On Current Requirements for the Spartan-II and Spartan-IIIE Families"](#).

## DC Input and Output Levels

Values for  $V_{IL}$  and  $V_{IH}$  are recommended input voltages. Values for  $V_{OL}$  and  $V_{OH}$  are guaranteed output voltages over the recommended operating conditions. Only selected standards are tested. These are chosen to ensure that all

standards meet their specifications. The selected standards are tested at minimum  $V_{CCO}$  with the respective  $I_{OL}$  and  $I_{OH}$  currents shown. Other standards are sample tested.

Input/Output Standard	$V_{IL}$		$V_{IH}$		$V_{OL}$	$V_{OH}$	$I_{OL}$	$I_{OH}$
	V, Min	V, Max	V, Min	V, Max	V, Max	V, Min	mA	mA
LVTTL <sup>(1)</sup>	-0.5	0.8	2.0	5.5	0.4	2.4	24	-24
LVCMOS2	-0.5	0.7	1.7	5.5	0.4	1.9	12	-12
PCI, 3.3V	-0.5	44% $V_{CCINT}$	60% $V_{CCINT}$	$V_{CCO} + 0.5$	10% $V_{CCO}$	90% $V_{CCO}$	Note (2)	Note (2)
PCI, 5.0V	-0.5	0.8	2.0	5.5	0.55	2.4	Note (2)	Note (2)
GTL	-0.5	$V_{REF} - 0.05$	$V_{REF} + 0.05$	3.6	0.4	N/A	40	N/A
GTL+	-0.5	$V_{REF} - 0.1$	$V_{REF} + 0.1$	3.6	0.6	N/A	36	N/A
HSTL I	-0.5	$V_{REF} - 0.1$	$V_{REF} + 0.1$	3.6	0.4	$V_{CCO} - 0.4$	8	-8
HSTL III	-0.5	$V_{REF} - 0.1$	$V_{REF} + 0.1$	3.6	0.4	$V_{CCO} - 0.4$	24	-8
HSTL IV	-0.5	$V_{REF} - 0.1$	$V_{REF} + 0.1$	3.6	0.4	$V_{CCO} - 0.4$	48	-8
SSTL3 I	-0.5	$V_{REF} - 0.2$	$V_{REF} + 0.2$	3.6	$V_{REF} - 0.6$	$V_{REF} + 0.6$	8	-8
SSTL3 II	-0.5	$V_{REF} - 0.2$	$V_{REF} + 0.2$	3.6	$V_{REF} - 0.8$	$V_{REF} + 0.8$	16	-16
SSTL2 I	-0.5	$V_{REF} - 0.2$	$V_{REF} + 0.2$	3.6	$V_{REF} - 0.6$	$V_{REF} + 0.6$	7.6	-7.6
SSTL2 II	-0.5	$V_{REF} - 0.2$	$V_{REF} + 0.2$	3.6	$V_{REF} - 0.8$	$V_{REF} + 0.8$	15.2	-15.2
CTT	-0.5	$V_{REF} - 0.2$	$V_{REF} + 0.2$	3.6	$V_{REF} - 0.4$	$V_{REF} + 0.4$	8	-8
AGP	-0.5	$V_{REF} - 0.2$	$V_{REF} + 0.2$	3.6	10% $V_{CCO}$	90% $V_{CCO}$	Note (2)	Note (2)

### Notes:

1.  $V_{OL}$  and  $V_{OH}$  for lower drive currents are sample tested.
2. Tested according to the relevant specifications.

## Switching Characteristics

Testing of switching parameters is modeled after testing methods specified by MIL-M-38510/605. All devices are 100% functionally tested. Internal timing parameters are derived from measuring internal test patterns. Listed below are representative values. For more specific, more precise, and worst-case guaranteed data, use the values reported

by the static timing analyzer (TRCE in the Xilinx Development System) and back-annotated to the simulation netlist. All timing parameters assume worst-case operating conditions (supply voltage and junction temperature). Values apply to all Spartan-II devices unless otherwise noted.

### Global Clock Input to Output Delay for LVTTL, with DLL (Pin-to-Pin)<sup>(1)</sup>

Symbol	Description	Device	Speed Grade			Units
			All	-6	-5	
			Min	Max	Max	
T <sub>ICKOF</sub> DLL	Global clock input to output delay using output flip-flop for LVTTL, 12 mA, fast slew rate, <i>with</i> DLL.	All		2.9	3.3	ns

**Notes:**

1. Listed above are representative values where one global clock input drives one vertical clock line in each accessible column, and where all accessible IOB and CLB flip-flops are clocked by the global clock net.
2. Output timing is measured at 1.4V with 35 pF external capacitive load for LVTTL. The 35 pF load does not apply to the Min values. For other I/O standards and different loads, see the tables **Constants for Calculating T<sub>IOOP</sub>** and **Delay Measurement Methodology**, page 10.
3. DLL output jitter is already included in the timing calculation.
4. For data *output* with different standards, adjust delays with the values shown in **IOB Output Delay Adjustments for Different Standards**, page 9. For a global clock input with standards other than LVTTL, adjust delays with values from the **I/O Standard Global Clock Input Adjustments**, page 11.

### Global Clock Input to Output Delay for LVTTL, without DLL (Pin-to-Pin)<sup>(1)</sup>

Symbol	Description	Device	Speed Grade			Units
			All	-6	-5	
			Min	Max	Max	
T <sub>ICKOF</sub>	Global clock input to output delay using output flip-flop for LVTTL, 12 mA, fast slew rate, <i>without</i> DLL.	XC2S15		4.5	5.4	ns
		XC2S30		4.5	5.4	ns
		XC2S50		4.5	5.4	ns
		XC2S100		4.6	5.5	ns
		XC2S150		4.6	5.5	ns
		XC2S200		4.7	5.6	ns

**Notes:**

1. Listed above are representative values where one global clock input drives one vertical clock line in each accessible column, and where all accessible IOB and CLB flip-flops are clocked by the global clock net.
2. Output timing is measured at 1.4V with 35 pF external capacitive load for LVTTL. The 35 pF load does not apply to the Min values. For other I/O standards and different loads, see the tables **Constants for Calculating T<sub>IOOP</sub>** and **Delay Measurement Methodology**, page 10.
3. For data *output* with different standards, adjust delays with the values shown in **IOB Output Delay Adjustments for Different Standards**, page 9. For a global clock input with standards other than LVTTL, adjust delays with values from the **I/O Standard Global Clock Input Adjustments**, page 11.

## Global Clock Setup and Hold for LVTTL Standard, *with* DLL (Pin-to-Pin)

Symbol	Description	Device	Speed Grade		Units
			-6	-5	
			Min	Min	
$T_{PSDLL} / T_{PHDLL}$	Input setup and hold time relative to global clock input signal for LVTTL standard, no delay, IFF, <sup>(1)</sup> with DLL	All	1.7 / 0	1.9 / 0	ns

**Notes:**

1. IFF = Input Flip-Flop or Latch
2. Setup time is measured relative to the Global Clock input signal with the fastest route and the lightest load. Hold time is measured relative to the Global Clock input signal with the slowest route and heaviest load.
3. DLL output jitter is already included in the timing calculation.
4. A zero hold time listing indicates no hold time or a negative hold time.
5. For data input with different standards, adjust the setup time delay by the values shown in **IOB Input Delay Adjustments for Different Standards**, page 7. For a global clock input with standards other than LVTTL, adjust delays with values from the **I/O Standard Global Clock Input Adjustments**, page 11.

## Global Clock Setup and Hold for LVTTL Standard, *without* DLL (Pin-to-Pin)

Symbol	Description	Device	Speed Grade		Units
			-6	-5	
			Min	Min	
$T_{PSFD} / T_{PHFD}$	Input setup and hold time relative to global clock input signal for LVTTL standard, no delay, IFF, <sup>(1)</sup> without DLL	XC2S15	2.2 / 0	2.7 / 0	ns
		XC2S30	2.2 / 0	2.7 / 0	ns
		XC2S50	2.2 / 0	2.7 / 0	ns
		XC2S100	2.3 / 0	2.8 / 0	ns
		XC2S150	2.4 / 0	2.9 / 0	ns
		XC2S200	2.4 / 0	3.0 / 0	ns

**Notes:**

1. IFF = Input Flip-Flop or Latch
2. Setup time is measured relative to the Global Clock input signal with the fastest route and the lightest load. Hold time is measured relative to the Global Clock input signal with the slowest route and heaviest load.
3. A zero hold time listing indicates no hold time or a negative hold time.
4. For data input with different standards, adjust the setup time delay by the values shown in **IOB Input Delay Adjustments for Different Standards**, page 7. For a global clock input with standards other than LVTTL, adjust delays with values from the **I/O Standard Global Clock Input Adjustments**, page 11.

## IOB Input Switching Characteristics<sup>(1)</sup>

Input delays associated with the pad are specified for LVTTL levels. For other standards, adjust the delays with the values shown in **IOB Input Delay Adjustments for Different Standards**, page 7.

Symbol	Description	Device	Speed Grade				Units	
			-6		-5			
			Min	Max	Min	Max		
<b>Propagation Delays</b>								
T <sub>IOPI</sub>	Pad to I output, no delay	All	-	0.8	-	1.0	ns	
T <sub>IOPID</sub>	Pad to I output, with delay	All	-	1.5	-	1.8	ns	
T <sub>IOPLI</sub>	Pad to output IQ via transparent latch, no delay	All	-	1.7	-	2.0	ns	
T <sub>IOPLID</sub>	Pad to output IQ via transparent latch, with delay	XC2S15	-	3.8	-	4.5	ns	
		XC2S30	-	3.8	-	4.5	ns	
		XC2S50	-	3.8	-	4.5	ns	
		XC2S100	-	3.8	-	4.5	ns	
		XC2S150	-	4.0	-	4.7	ns	
		XC2S200	-	4.0	-	4.7	ns	
<b>Sequential Delays</b>								
T <sub>IOCKIQ</sub>	Clock CLK to output IQ	All	-	0.7	-	0.8	ns	
<b>Setup/Hold Times with Respect to Clock CLK<sup>(2)</sup></b>								
T <sub>IOPICK</sub> / T <sub>IOICKP</sub>	Pad, no delay	All	1.7 / 0	-	1.9 / 0	-	ns	
T <sub>IOPIKD</sub> / T <sub>IOICKPD</sub>	Pad, with delay <sup>(1)</sup>	XC2S15	3.8 / 0	-	4.4 / 0	-	ns	
		XC2S30	3.8 / 0	-	4.4 / 0	-	ns	
		XC2S50	3.8 / 0	-	4.4 / 0	-	ns	
		XC2S100	3.8 / 0	-	4.4 / 0	-	ns	
		XC2S150	3.9 / 0	-	4.6 / 0	-	ns	
		XC2S200	3.9 / 0	-	4.6 / 0	-	ns	
T <sub>IOICECK</sub> / T <sub>IOCKICE</sub>	ICE input	All	0.9 / 0.01	-	0.9 / 0.01	-	ns	
<b>Set/Reset Delays</b>								
T <sub>IOSRCKI</sub>	SR input (IFF, synchronous)	All	-	1.1	-	1.2	ns	
T <sub>IOSRIQ</sub>	SR input to IQ (asynchronous)	All	-	1.5	-	1.7	ns	
T <sub>GSRQ</sub>	GSR to output IQ	All	-	9.9	-	11.7	ns	

**Notes:**

1. Input timing for LVTTL is measured at 1.4V. For other I/O standards, see the table **Delay Measurement Methodology**, page 10.
2. A zero hold time listing indicates no hold time or a negative hold time.

## IOB Input Delay Adjustments for Different Standards<sup>(1)</sup>

Input delays associated with the pad are specified for LVTTL. For other standards, adjust the delays by the values shown. A delay adjusted in this way constitutes a worst-case limit.

Symbol	Description	Standard	Speed Grade		Units
			-6	-5	
<b>Data Input Delay Adjustments</b>					
$T_{ILVTTL}$	Standard-specific data input delay adjustments	LVTTL	0	0	ns
$T_{ILVCMOS2}$		LVCMOS2	-0.04	-0.05	ns
$T_{IPCI33_3}$		PCI, 33 MHz, 3.3V	-0.11	-0.13	ns
$T_{IPCI33_5}$		PCI, 33 MHz, 5.0V	0.26	0.30	ns
$T_{IPCI66_3}$		PCI, 66 MHz, 3.3V	-0.11	-0.13	ns
$T_{IGTL}$		GTL	0.20	0.24	ns
$T_{IGTLP}$		GTL+	0.11	0.13	ns
$T_{IHSTL}$		HSTL	0.03	0.04	ns
$T_{ISSTL2}$		SSTL2	-0.08	-0.09	ns
$T_{ISSTL3}$		SSTL3	-0.04	-0.05	ns
$T_{ICTT}$		CTT	0.02	0.02	ns
$T_{IAGP}$		AGP	-0.06	-0.07	ns

### Notes:

1. Input timing for LVTTL is measured at 1.4V. For other I/O standards, see the table **Delay Measurement Methodology**, page 10.

## IOB Output Switching Characteristics

Output delays terminating at a pad are specified for LVTTL with 12 mA drive and fast slew rate. For other standards, adjust the delays with the values shown in **IOB Output Delay Adjustments for Different Standards, page 9.**

Symbol	Description	Speed Grade				Units	
		-6		-5			
		Min	Max	Min	Max		
<b>Propagation Delays</b>							
$T_{IOOP}$	O input to pad	-	2.9	-	3.4	ns	
$T_{IOOLP}$	O input to pad via transparent latch	-	3.4	-	4.0	ns	
<b>3-state Delays</b>							
$T_{IOTHZ}$	T input to pad high-impedance <sup>(1)</sup>	-	2.0	-	2.3	ns	
$T_{IOTON}$	T input to valid data on pad	-	3.0	-	3.6	ns	
$T_{IOTLPHZ}$	T input to pad high impedance via transparent latch <sup>(1)</sup>	-	2.5	-	2.9	ns	
$T_{IOTLPON}$	T input to valid data on pad via transparent latch	-	3.5	-	4.2	ns	
$T_{GTS}$	GTS to pad high impedance <sup>(1)</sup>	-	5.0	-	5.9	ns	
<b>Sequential Delays</b>							
$T_{ILOCKP}$	Clock CLK to pad	-	2.9	-	3.4	ns	
$T_{ILOCKHZ}$	Clock CLK to pad high impedance (synchronous) <sup>(1)</sup>	-	2.3	-	2.7	ns	
$T_{ILOCKON}$	Clock CLK to valid data on pad (synchronous)	-	3.3	-	4.0	ns	
<b>Setup/Hold Times with Respect to Clock CLK<sup>(2)</sup></b>							
$T_{IOOCK} / T_{ILOCKO}$	O input	1.1 / 0	-	1.3 / 0	-	ns	
$T_{IOOCECK} / T_{ILOCKOCE}$	OCE input	0.9 / 0.01	-	0.9 / 0.01	-	ns	
$T_{IOSRCKO} / T_{ILOCKOSR}$	SR input (OFF)	1.2 / 0	-	1.3 / 0	-	ns	
$T_{IOTCK} / T_{ILOCKT}$	3-state setup times, T input	0.8 / 0	-	0.9 / 0	-	ns	
$T_{IOTCECK} / T_{ILOCKTCE}$	3-state setup times, TCE input	1.0 / 0	-	1.0 / 0	-	ns	
$T_{IOSRCKT} / T_{ILOCKTSR}$	3-state setup times, SR input (TFF)	1.1 / 0	-	1.2 / 0	-	ns	
<b>Set/Reset Delays</b>							
$T_{IOSRP}$	SR input to pad (asynchronous)	-	3.7	-	4.4	ns	
$T_{IOSRHZ}$	SR input to pad high impedance (asynchronous) <sup>(1)</sup>	-	3.1	-	3.7	ns	
$T_{IOSRON}$	SR input to valid data on pad (asynchronous)	-	4.1	-	4.9	ns	
$T_{IOGSRQ}$	GSR to pad	-	9.9	-	11.7	ns	

**Notes:**

1. Three-state turn-off delays should not be adjusted.
2. A zero hold time listing indicates no hold time or a negative hold time.

## IOB Output Delay Adjustments for Different Standards<sup>(1)</sup>

Output delays terminating at a pad are specified for LVTTL with 12 mA drive and fast slew rate. For other standards, adjust the delays by the values shown. A delay adjusted in this way constitutes a worst-case limit.

Symbol	Description	Standard	Speed Grade		Units
			-6	-5	
<b>Output Delay Adjustments (Adj)</b>					
T <sub>OLVTTL_S2</sub>	Standard-specific adjustments for output delays terminating at pads (based on standard capacitive load, C <sub>SL</sub> )	LVTTL, Slow, 2 mA	14.2	16.9	ns
T <sub>OLVTTL_S4</sub>		4 mA	7.2	8.6	ns
T <sub>OLVTTL_S6</sub>		6 mA	4.7	5.5	ns
T <sub>OLVTTL_S8</sub>		8 mA	2.9	3.5	ns
T <sub>OLVTTL_S12</sub>		12 mA	1.9	2.2	ns
T <sub>OLVTTL_S16</sub>		16 mA	1.7	2.0	ns
T <sub>OLVTTL_S24</sub>		24 mA	1.3	1.5	ns
T <sub>OLVTTL_F2</sub>	LVTTL, Fast, 2 mA	12.6	15.0	ns	
T <sub>OLVTTL_F4</sub>		4 mA	5.1	6.1	ns
T <sub>OLVTTL_F6</sub>		6 mA	3.0	3.6	ns
T <sub>OLVTTL_F8</sub>		8 mA	1.0	1.2	ns
T <sub>OLVTTL_F12</sub>		12 mA	0	0	ns
T <sub>OLVTTL_F16</sub>		16 mA	-0.1	-0.1	ns
T <sub>OLVTTL_F24</sub>		24 mA	-0.1	-0.2	ns
T <sub>OLVCMOS2</sub>	LVCMOS2	0.2	0.2	ns	
T <sub>OPCI33_3</sub>	PCI, 33 MHz, 3.3V	2.4	2.9	ns	
T <sub>OPCI33_5</sub>	PCI, 33 MHz, 5.0V	2.9	3.5	ns	
T <sub>OPCI66_3</sub>	PCI, 66 MHz, 3.3V	-0.3	-0.4	ns	
T <sub>OGL</sub>	GTL	0.6	0.7	ns	
T <sub>OGLP</sub>	GTL+	0.9	1.1	ns	
T <sub>OHSTL_I</sub>	HSTL I	-0.4	-0.5	ns	
T <sub>OHSTL_III</sub>	HSTL III	-0.8	-1.0	ns	
T <sub>OHSTL_IV</sub>	HSTL IV	-0.9	-1.1	ns	
T <sub>OSSTL2_I</sub>	SSTL2 I	-0.4	-0.5	ns	
T <sub>OSSTL2_II</sub>	SSTL2 II	-0.8	-1.0	ns	
T <sub>OSSTL3_I</sub>	SSTL3 I	-0.4	-0.5	ns	
T <sub>OSSTL3_II</sub>	SSTL3 II	-0.9	-1.1	ns	
T <sub>OCTT</sub>	CTT	-0.5	-0.6	ns	
T <sub>OAGP</sub>	AGP	-0.8	-1.0	ns	

### Notes:

1. Output timing is measured at 1.4V with 35 pF external capacitive load for LVTTL. For other I/O standards and different loads, see the tables **Constants for Calculating T<sub>loop</sub>** and **Delay Measurement Methodology, page 10**.

## Calculation of $T_{IOOP}$ as a Function of Capacitance

$T_{IOOP}$  is the propagation delay from the O Input of the IOB to the pad. The values for  $T_{IOOP}$  are based on the standard capacitive load ( $C_{SL}$ ) for each I/O standard as listed in the table **Constants for Calculating  $T_{IOOP}$** , below.

For other capacitive loads, use the formulas below to calculate an adjusted propagation delay,  $T_{IOOP1}$ .

$$T_{IOOP1} = T_{IOOP} + \text{Adj} + (C_{LOAD} - C_{SL}) * F_L$$

Where:

Adj is selected from **IOB Output Delay Adjustments for Different Standards**, page 9, according to the I/O standard used

$C_{LOAD}$  is the capacitive load for the design

$F_L$  is the capacitance scaling factor

## Delay Measurement Methodology

Standard	$V_L^{(1)}$	$V_H^{(1)}$	Meas. Point	$V_{REF}$ Typ <sup>(2)</sup>
LVTTL	0	3	1.4	-
LVCMOS2	0	2.5	1.125	-
PCI33_5	Per PCI Spec			-
PCI33_3	Per PCI Spec			-
PCI66_3	Per PCI Spec			-
GTL	$V_{REF} - 0.2$	$V_{REF} + 0.2$	$V_{REF}$	0.80
GTL+	$V_{REF} - 0.2$	$V_{REF} + 0.2$	$V_{REF}$	1.0
HSTL Class I	$V_{REF} - 0.5$	$V_{REF} + 0.5$	$V_{REF}$	0.75
HSTL Class III	$V_{REF} - 0.5$	$V_{REF} + 0.5$	$V_{REF}$	0.90
HSTL Class IV	$V_{REF} - 0.5$	$V_{REF} + 0.5$	$V_{REF}$	0.90
SSTL3 I and II	$V_{REF} - 1.0$	$V_{REF} + 1.0$	$V_{REF}$	1.5
SSTL2 I and II	$V_{REF} - 0.75$	$V_{REF} + 0.75$	$V_{REF}$	1.25
CTT	$V_{REF} - 0.2$	$V_{REF} + 0.2$	$V_{REF}$	1.5
AGP	$V_{REF} - (0.2 \times V_{CCO})$	$V_{REF} + (0.2 \times V_{CCO})$	$V_{REF}$	Per AGP Spec

### Notes:

1. Input waveform switches between  $V_L$  and  $V_H$ .
2. Measurements are made at  $V_{REF}$  Typ, Maximum, and Minimum. Worst-case values are reported.
3. I/O parameter measurements are made with the capacitance values shown in the previous table, **Constants for Calculating  $T_{IOOP}$** . See Xilinx application note XAPP179 for the appropriate terminations.
4. I/O standard measurements are reflected in the IBIS model information except where the IBIS format precludes it.

## Constants for Calculating $T_{IOOP}$

Standard	$C_{SL}^{(1)}$ (pF)	$F_L$ (ns/pF)
LVTTL Fast Slew Rate, 2 mA drive	35	0.41
LVTTL Fast Slew Rate, 4 mA drive	35	0.20
LVTTL Fast Slew Rate, 6 mA drive	35	0.13
LVTTL Fast Slew Rate, 8 mA drive	35	0.079
LVTTL Fast Slew Rate, 12 mA drive	35	0.044
LVTTL Fast Slew Rate, 16 mA drive	35	0.043
LVTTL Fast Slew Rate, 24 mA drive	35	0.033
LVTTL Slow Slew Rate, 2 mA drive	35	0.41
LVTTL Slow Slew Rate, 4 mA drive	35	0.20
LVTTL Slow Slew Rate, 6 mA drive	35	0.100
LVTTL Slow Slew Rate, 8 mA drive	35	0.086
LVTTL Slow Slew Rate, 12 mA drive	35	0.058
LVTTL Slow Slew Rate, 16 mA drive	35	0.050
LVTTL Slow Slew Rate, 24 mA drive	35	0.048
LVCMOS2	35	0.041
PCI 33 MHz 5V	50	0.050
PCI 33 MHZ 3.3V	10	0.050
PCI 66 MHz 3.3V	10	0.033
GTL	0	0.014
GTL+	0	0.017
HSTL Class I	20	0.022
HSTL Class III	20	0.016
HSTL Class IV	20	0.014
SSTL2 Class I	30	0.028
SSTL2 Class II	30	0.016
SSTL3 Class I	30	0.029
SSTL3 Class II	30	0.016
CTT	20	0.035
AGP	10	0.037

### Notes:

1. I/O parameter measurements are made with the capacitance values shown above. See Xilinx application note XAPP179 for the appropriate terminations.
2. I/O standard measurements are reflected in the IBIS model information except where the IBIS format precludes it.

## Clock Distribution Guidelines<sup>(1)</sup>

Symbol	Description	Speed Grade		Units
		-6	-5	
		Max	Max	
<b>GCLK Clock Skew</b>				
T <sub>GSKEWIOB</sub>	Global clock skew between IOB flip-flops	0.13	0.14	ns

**Notes:**

- These clock distribution delays are provided for guidance only. They reflect the delays encountered in a typical design under worst-case conditions. Precise values for a particular design are provided by the timing analyzer.

## Clock Distribution Switching Characteristics

T<sub>GPIO</sub> is specified for LVTTL levels. For other standards, adjust T<sub>GPIO</sub> with the values shown in **I/O Standard Global Clock Input Adjustments**.

Symbol	Description	Speed Grade		Units
		-6	-5	
		Max	Max	
<b>GCLK IOB and Buffer</b>				
T <sub>GPIO</sub>	Global clock pad to output	0.7	0.8	ns
T <sub>GIO</sub>	Global clock buffer I input to O output	0.7	0.8	ns

## I/O Standard Global Clock Input Adjustments

Delays associated with a global clock input pad are specified for LVTTL levels. For other standards, adjust the delays by the values shown. A delay adjusted in the way constitutes a worst-case limit.

Symbol	Description	Standard	Speed Grade		Units
			-6	-5	
<b>Data Input Delay Adjustments</b>					
T <sub>GPLVTTL</sub>	Standard-specific global clock input delay adjustments	LVTTL	0	0	ns
T <sub>GPLVCMOS2</sub>		LVCMOS2	-0.04	-0.05	ns
T <sub>GPPCI33_3</sub>		PCI, 33 MHz, 3.3V	-0.11	-0.13	ns
T <sub>GPPCI33_5</sub>		PCI, 33 MHz, 5.0V	0.26	0.30	ns
T <sub>GPPCI66_3</sub>		PCI, 66 MHz, 3.3V	-0.11	-0.13	ns
T <sub>GPGTL</sub>		GTL	0.80	0.84	ns
T <sub>GPGTLP</sub>		GTL+	0.71	0.73	ns
T <sub>GPHSTL</sub>		HSTL	0.63	0.64	ns
T <sub>GPSSTL2</sub>		SSTL2	0.52	0.51	ns
T <sub>GPSSTL3</sub>		SSTL3	0.56	0.55	ns
T <sub>GPCTT</sub>		CTT	0.62	0.62	ns
T <sub>GPAGP</sub>		AGP	0.54	0.53	ns

**Notes:**

- Input timing for GPLVTTL is measured at 1.4V. For other I/O standards, see the table **Delay Measurement Methodology**, page 10.

## DLL Timing Parameters

Switching parameters testing is modeled after testing methods specified by MIL-M-38510/605; all devices are 100 percent functionally tested. Because of the difficulty in directly measuring many internal timing parameters, those parame-

ters are derived from benchmark timing patterns. The following guidelines reflect worst-case values across the recommended operating conditions.

Symbol	Description	Speed Grade				Units	
		-6		-5			
		Min	Max	Min	Max		
$F_{CLKINHF}$	Input clock frequency (CLKDLLHF)	60	200	60	180	MHz	
$F_{CLKINLF}$	Input clock frequency (CLKDLL)	25	100	25	90	MHz	
$T_{DLLPWHF}$	Input clock pulse width (CLKDLLHF)	2.0	-	2.4	-	ns	
$T_{DLLPWLF}$	Input clock pulse width (CLKDLL)	2.5	-	3.0	-	ns	

## DLL Clock Tolerance, Jitter, and Phase Information

All DLL output jitter and phase specifications were determined through statistical measurement at the package pins using a clock mirror configuration and matched drivers.

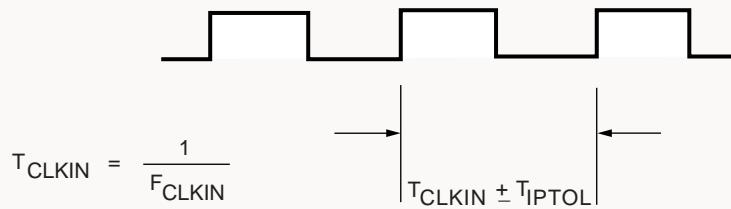
Figure 1, page 13, provides definitions for various parameters in the table below.

Symbol	Description	$F_{CLKIN}$	CLKDLLHF		CLKDLL		Units
			Min	Max	Min	Max	
$T_{IPTOL}$	Input clock period tolerance		-	1.0	-	1.0	ns
$T_{IJITCC}$	Input clock jitter tolerance (cycle-to-cycle)		-	$\pm 150$	-	$\pm 300$	ps
$T_{LOCK}$	Time required for DLL to acquire lock	> 60 MHz	-	20	-	20	$\mu s$
		50-60 MHz	-	-	-	25	$\mu s$
		40-50 MHz	-	-	-	50	$\mu s$
		30-40 MHz	-	-	-	90	$\mu s$
		25-30 MHz	-	-	-	120	$\mu s$
$T_{OJITCC}$	Output jitter (cycle-to-cycle) for any DLL clock output <sup>(1)</sup>		-	$\pm 60$	-	$\pm 60$	ps
$T_{PHIO}$	Phase offset between CLKIN and CLKO <sup>(2)</sup>		-	$\pm 100$	-	$\pm 100$	ps
$T_{PHOO}$	Phase offset between clock outputs on the DLL <sup>(3)</sup>		-	$\pm 140$	-	$\pm 140$	ps
$T_{PHIOM}$	Maximum phase difference between CLKIN and CLKO <sup>(4)</sup>		-	$\pm 160$	-	$\pm 160$	ps
$T_{PHOOM}$	Maximum phase difference between clock outputs on the DLL <sup>(5)</sup>		-	$\pm 200$	-	$\pm 200$	ps

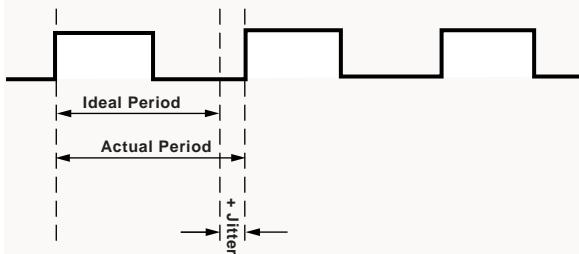
### Notes:

1. **Output Jitter** is cycle-to-cycle jitter measured on the DLL output clock, *excluding* input clock jitter.
2. **Phase Offset between CLKIN and CLKO** is the worst-case fixed time difference between rising edges of CLKIN and CLKO, *excluding* output jitter and input clock jitter.
3. **Phase Offset between Clock Outputs on the DLL** is the worst-case fixed time difference between rising edges of any two DLL outputs, *excluding* Output Jitter and input clock jitter.
4. **Maximum Phase Difference between CLKIN and CLKO** is the sum of Output Jitter and Phase Offset between CLKIN and CLKO, or the greatest difference between CLKIN and CLKO rising edges due to DLL alone (*excluding* input clock jitter).
5. **Maximum Phase Difference between Clock Outputs on the DLL** is the sum of Output Jitter and Phase Offset between any DLL clock outputs, or the greatest difference between any two DLL output rising edges due to DLL alone (*excluding* input clock jitter).

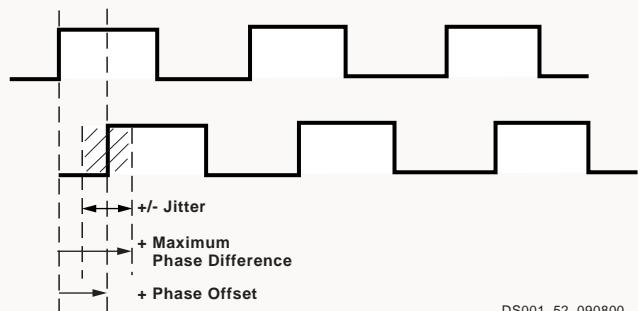
**Period Tolerance:** the allowed input clock period change in nanoseconds.



**Output Jitter:** the difference between an ideal reference clock edge and the actual design.



#### Phase Offset and Maximum Phase Difference



DS001\_52\_090800

Figure 1: Period Tolerance and Clock Jitter

## CLB Switching Characteristics

Delays originating at F/G inputs vary slightly according to the input used. The values listed below are worst-case. Precise values are provided by the timing analyzer.

Symbol	Description	Speed Grade				Units	
		-6		-5			
		Min	Max	Min	Max		
<b>Combinatorial Delays</b>							
T <sub>ILO</sub>	4-input function: F/G inputs to X/Y outputs	-	0.6	-	0.7	ns	
T <sub>IF5</sub>	5-input function: F/G inputs to F5 output	-	0.7	-	0.9	ns	
T <sub>IF5X</sub>	5-input function: F/G inputs to X output	-	0.9	-	1.1	ns	
T <sub>IF6Y</sub>	6-input function: F/G inputs to Y output via F6 MUX	-	1.0	-	1.1	ns	
T <sub>F5INY</sub>	6-input function: F5IN input to Y output	-	0.4	-	0.4	ns	
T <sub>IFNCTL</sub>	Incremental delay routing through transparent latch to XQ/YQ outputs	-	0.7	-	0.9	ns	
T <sub>BYYB</sub>	BY input to YB output	-	0.6	-	0.7	ns	
<b>Sequential Delays</b>							
T <sub>CKO</sub>	FF clock CLK to XQ/YQ outputs	-	1.1	-	1.3	ns	
T <sub>CKLO</sub>	Latch clock CLK to XQ/YQ outputs	-	1.2	-	1.5	ns	
<b>Setup/Hold Times with Respect to Clock CLK<sup>(1)</sup></b>							
T <sub>ICK / T<sub>CKI</sub></sub>	4-input function: F/G inputs	1.3 / 0	-	1.4 / 0	-	ns	
T <sub>IF5CK / T<sub>CKIF5</sub></sub>	5-input function: F/G inputs	1.6 / 0	-	1.8 / 0	-	ns	
T <sub>F5INCK / T<sub>CKF5IN</sub></sub>	6-input function: F5IN input	1.0 / 0	-	1.1 / 0	-	ns	
T <sub>IF6CK / T<sub>CKIF6</sub></sub>	6-input function: F/G inputs via F6 MUX	1.6 / 0	-	1.8 / 0	-	ns	
T <sub>DICK / T<sub>CKDI</sub></sub>	BX/BY inputs	0.8 / 0	-	0.8 / 0	-	ns	
T <sub>CECK / T<sub>CKCE</sub></sub>	CE input	0.9 / 0	-	0.9 / 0	-	ns	
T <sub>RCK / T<sub>CKR</sub></sub>	SR/BY inputs (synchronous)	0.8 / 0	-	0.8 / 0	-	ns	
<b>Clock CLK</b>							
T <sub>CH</sub>	Minimum pulse width, High	-	1.9	-	1.9	ns	
T <sub>CL</sub>	Minimum pulse width, Low	-	1.9	-	1.9	ns	
<b>Set/Reset</b>							
T <sub>RPW</sub>	Minimum pulse width, SR/BY inputs	-	3.1	-	3.1	ns	
T <sub>RQ</sub>	Delay from SR/BY inputs to XQ/YQ outputs (asynchronous)	-	1.1	-	1.3	ns	
T <sub>ILOGSRQ</sub>	Delay from GSR to XQ/YQ outputs	-	9.9	-	11.7	ns	
F <sub>TOG</sub>	Toggle frequency (for export control)	-	263	-	263	MHz	

### Notes:

1. A zero hold time listing indicates no hold time or a negative hold time.

## CLB Arithmetic Switching Characteristics

Setup times not listed explicitly can be approximated by decreasing the combinatorial delays by the setup time adjustment listed. Precise values are provided by the timing analyzer.

Symbol	Description	Speed Grade				Units	
		-6		-5			
		Min	Max	Min	Max		
<b>Combinatorial Delays</b>							
T <sub>OPX</sub>	F operand inputs to X via XOR	-	0.8	-	0.9	ns	
T <sub>OPXB</sub>	F operand input to XB output	-	1.3	-	1.5	ns	
T <sub>OPY</sub>	F operand input to Y via XOR	-	1.7	-	2.0	ns	
T <sub>OPYB</sub>	F operand input to YB output	-	1.7	-	2.0	ns	
T <sub>OPCYF</sub>	F operand input to COUT output	-	1.3	-	1.5	ns	
T <sub>OPGY</sub>	G operand inputs to Y via XOR	-	0.9	-	1.1	ns	
T <sub>OPGYB</sub>	G operand input to YB output	-	1.6	-	2.0	ns	
T <sub>OPCYG</sub>	G operand input to COUT output	-	1.2	-	1.4	ns	
T <sub>BXCY</sub>	BX initialization input to COUT	-	0.9	-	1.0	ns	
T <sub>CINX</sub>	CIN input to X output via XOR	-	0.4	-	0.5	ns	
T <sub>CINXB</sub>	CIN input to XB	-	0.1	-	0.1	ns	
T <sub>CINY</sub>	CIN input to Y via XOR	-	0.5	-	0.6	ns	
T <sub>CINYB</sub>	CIN input to YB	-	0.6	-	0.7	ns	
T <sub>BYP</sub>	CIN input to COUT output	-	0.1	-	0.1	ns	
<b>Multiplier Operation</b>							
T <sub>FANDXB</sub>	F1/2 operand inputs to XB output via AND	-	0.5	-	0.5	ns	
T <sub>FANDYB</sub>	F1/2 operand inputs to YB output via AND	-	0.9	-	1.1	ns	
T <sub>FANDCY</sub>	F1/2 operand inputs to COUT output via AND	-	0.5	-	0.6	ns	
T <sub>GANDYB</sub>	G1/2 operand inputs to YB output via AND	-	0.6	-	0.7	ns	
T <sub>GANDCY</sub>	G1/2 operand inputs to COUT output via AND	-	0.2	-	0.2	ns	
<b>Setup/Hold Times with Respect to Clock CLK<sup>(1)</sup></b>							
T <sub>CCKX / T<sub>CKCX</sub></sub>	CIN input to FFX	1.1 / 0	-	1.2 / 0	-	ns	
T <sub>CCKY / T<sub>CKCY</sub></sub>	CIN input to FFY	1.2 / 0	-	1.3 / 0	-	ns	

**Notes:**

1. A zero hold time listing indicates no hold time or a negative hold time.

## CLB Distributed RAM Switching Characteristics

Symbol	Description	Speed Grade				Units	
		-6		-5			
		Min	Max	Min	Max		
<b>Sequential Delays</b>							
$T_{SHCKO16}$	Clock CLK to X/Y outputs (WE active, 16 x 1 mode)	-	2.2	-	2.6	ns	
$T_{SHCKO32}$	Clock CLK to X/Y outputs (WE active, 32 x 1 mode)	-	2.5	-	3.0	ns	
<b>Setup/Hold Times with Respect to Clock CLK<sup>(1)</sup></b>							
$T_{AS} / T_{AH}$	F/G address inputs	0.7 / 0	-	0.7 / 0	-	ns	
$T_{DS} / T_{DH}$	BX/BY data inputs (DIN)	0.8 / 0	-	0.9 / 0	-	ns	
$T_{WS} / T_{WH}$	CE input (WS)	0.9 / 0	-	1.0 / 0	-	ns	
<b>Clock CLK</b>							
$T_{WPH}$	Minimum pulse width, High	-	2.9	-	2.9	ns	
$T_{WPL}$	Minimum pulse width, Low	-	2.9	-	2.9	ns	
$T_{WC}$	Minimum clock period to meet address write cycle time	-	5.8	-	5.8	ns	

**Notes:**

1. A zero hold time listing indicates no hold time or a negative hold time.

## CLB Shift Register Switching Characteristics

Symbol	Description	Speed Grade				Units	
		-6		-5			
		Min	Max	Min	Max		
<b>Sequential Delays</b>							
$T_{REG}$	Clock CLK to X/Y outputs	-	3.47	-	3.88	ns	
<b>Setup Times with Respect to Clock CLK</b>							
$T_{SHDICK}$	BX/BY data inputs (DIN)	0.8	-	0.9	-	ns	
$T_{SHCECK}$	CE input (WS)	0.9	-	1.0	-	ns	
<b>Clock CLK</b>							
$T_{SRPH}$	Minimum pulse width, High	-	2.9	-	2.9	ns	
$T_{SRPL}$	Minimum pulse width, Low	-	2.9	-	2.9	ns	

## Block RAM Switching Characteristics

Symbol	Description	Speed Grade				Units	
		-6		-5			
		Min	Max	Min	Max		
<b>Sequential Delays</b>							
T <sub>BCKO</sub>	Clock CLK to DOUT output	-	3.4	-	4.0	ns	
<b>Setup/Hold Times with Respect to Clock CLK<sup>(1)</sup></b>							
T <sub>BACK</sub> / T <sub>BCKA</sub>	ADDR inputs	1.4 / 0	-	1.4 / 0	-	ns	
T <sub>BDCK</sub> / T <sub>BCKD</sub>	DIN inputs	1.4 / 0	-	1.4 / 0	-	ns	
T <sub>BECK</sub> / T <sub>BCKE</sub>	EN inputs	2.9 / 0	-	3.2 / 0	-	ns	
T <sub>BRCK</sub> / T <sub>BCKR</sub>	RST input	2.7 / 0	-	2.9 / 0	-	ns	
T <sub>BWCK</sub> / T <sub>BCKW</sub>	WEN input	2.6 / 0	-	2.8 / 0	-	ns	
<b>Clock CLK</b>							
T <sub>BPWH</sub>	Minimum pulse width, High	-	1.9	-	1.9	ns	
T <sub>BPWL</sub>	Minimum pulse width, Low	-	1.9	-	1.9	ns	
T <sub>BCCS</sub>	CLKA -> CLKB setup time for different ports	-	3.0	-	4.0	ns	

**Notes:**

1. A zero hold time listing indicates no hold time or a negative hold time.

## TBUF Switching Characteristics

Symbol	Description	Speed Grade		Units	
		-6			
		Max	Max		
<b>Combinatorial Delays</b>					
T <sub>IO</sub>	IN input to OUT output	0	0	ns	
T <sub>OFF</sub>	TRI input to OUT output high impedance	0.1	0.2	ns	
T <sub>ON</sub>	TRI input to valid data on OUT output	0.1	0.2	ns	

## JTAG Test Access Port Switching Characteristics

Symbol	Description	Speed Grade				Units	
		-6		-5			
		Min	Max	Min	Max		
<b>Setup and Hold Times with Respect to TCK</b>							
T <sub>TAPTCK</sub> / T <sub>TCKTAP</sub>	TMS and TDI setup and hold times	4.0 / 2.0	-	4.0 / 2.0	-	ns	
<b>Sequential Delays</b>							
T <sub>TCKTDO</sub>	Output delay from clock TCK to output TDO	-	11.0	-	11.0	ns	
F <sub>TCK</sub>	Maximum TCK clock frequency	-	33	-	33	MHz	

## Revision History

Version No.	Date	Description
2.0	09/18/00	Sectioned the Spartan-II Family data sheet into four modules. Updated timing to reflect the latest speed files. Added current supply numbers and XC2S200 -5 timing numbers. Approved -5 timing numbers as preliminary information with exceptions as noted.
2.1	11/02/00	Removed Power Down feature.
2.2	01/19/01	DC and timing numbers updated to Preliminary for the XC2S50 and XC2S100. Industrial power-on current specifications and -6 DLL timing numbers added. Power-on specification clarified.
2.3	03/09/01	Added note on power sequencing. Clarified power-on current requirement.
2.4	08/28/01	Added -6 preliminary timing. Added typical and industrial standby current numbers. Specified min. power-on current by junction temperature instead of by device type (Commercial vs. Industrial). Eliminated minimum $V_{CCINT}$ ramp time requirement. Removed footnote limiting DLL operation to the Commercial temperature range.
2.5	07/26/02	Clarified that I/O leakage current is specified over the Recommended Operating Conditions for $V_{CCINT}$ and $V_{CCO}$ .
2.6	08/26/02	Added references for XAPP450 to Power-On Current Specification.

## The Spartan-II Family Data Sheet

DS001-1, *Spartan-II 2.5V FPGA Family: Introduction and Ordering Information* (Module 1)

DS001-2, *Spartan-II 2.5V FPGA Family: Functional Description* (Module 2)

DS001-3, *Spartan-II 2.5V FPGA Family: DC and Switching Characteristics* (Module 3)

DS001-4, *Spartan-II 2.5V FPGA Family: Pinout Tables* (Module 4)